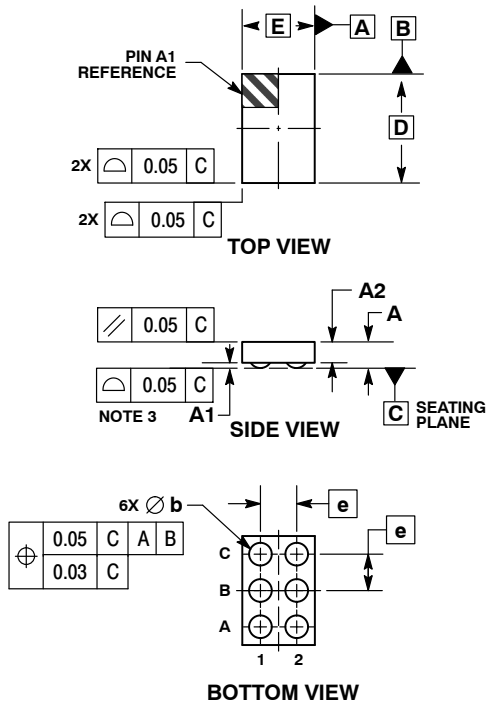




SCALE 4:1

**WLCSP6, 1.20x0.80**  
CASE 567MV  
ISSUE B

DATE 05 JUN 2018


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

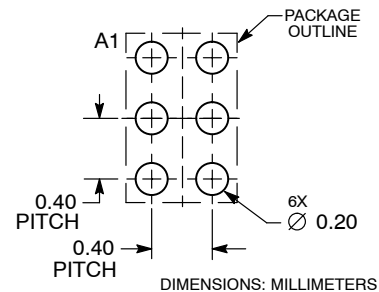
MILLIMETERS		
DIM	MIN	MAX
A	---	0.33
A1	0.04	0.08
A2	0.23	REF
b	0.24	0.30
D	1.20	BSC
E	0.80	BSC
e	0.40	BSC

**GENERIC MARKING DIAGRAM\***


XX = Specific Device Code

M = Month Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

**RECOMMENDED SOLDERING FOOTPRINT\***


\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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